RELIABILITY REPORT

FOR

MAX4751EGE+

PLASTIC ENCAPSULATED DEVICES

November 21, 2008

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
Ken Wendel
Quality Assurance
Director, Reliability Engineering

Conclusion

The MAX4751EGE+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX4751/MAX4752/MAX4753 are low on-resistance, low-voltage, quad, single-pole/single-throw (SPST) analog switches that operate from a single +1.6V to +3.6V supply. These devices have fast switching speeds (tON = 30ns, tOFF = 25ns), handle Rail-to-Rail analog signals, and consume less than 1µW of quiescent power. The MAX4753 has break-before-make switching. When powered from a +3V supply, the MAX4751/MAX4752/MAX4753 feature low 0.9 (max) on-resistance (RON), with 0.12 (max) RON matching and 0.1 (max) RON flatness. The digital input is 1.8V CMOS compatible when using a single +3V supply. The MAX4751 has four normally open (NO) switches, the MAX4752 has four normally closed (NC) switches, and the MAX4753 has two NO and two NC switches. The MAX4751/MAX4752/MAX4753 are available in 3mm x 3mm, 16-pin QFN and 14-pin TSSOP packages.

II. Manufacturing Information

A. Description/Function:	0.9 , Low-Voltage, Single-Supply Quad SPST Analog Switches
B. Process:	0.35UM 2 Poly 3 Metal CMOS (TS352P3M)
C. Number of Device Transistors:	
D. Fabrication Location:	Taiwan
E. Assembly Location:	ATK Korea
F. Date of Initial Production:	April 27, 2002

III. Packaging Information

A. Package Type:	16-pin QFN 3x3
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1201-0249
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	66°C/W
K. Single Layer Theta Jc:	15.1°C/W
L. Multi Layer Theta Ja:	59.3°C/W
M. Multi Layer Theta Jc:	15.1°C/W

IV. Die Information

B. Passivation:	Silicon Dioxide/Silicon Nitride
C. Interconnect:	Al/Cu
D. Backside Metallization:	None
E. Minimum Metal Width:	0.35 um
F. Minimum Metal Spacing:	0.35 um
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	Silicon Dioxide
I. Die Separation Method:	Saw

V. Quality Assurance Information

A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)
Bryan Preeshl (Managing Director of QA)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the biased (static) life test are pending. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 44 \times 2} \text{ (Chi square value for MTTF upper limit)}$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 24.4 \times 10^{-9}$

λ = 24.4 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the TS352P3M Process results in a FIT Rate of 0.43 @ 25C and 7.50 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The AH84 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1

Reliability Evaluation Test Results

MAX4751EGE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = Biased Time = 192 hrs.	DC Parameters & functionality	44	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data